



NSAI
Standards

Irish Standard
I.S. EN IEC 61190-1-3:2018

Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solder for electronic soldering applications

I.S. EN IEC 61190-1-3:2018

Incorporating amendments/corrigenda/National Annexes issued since publication:

The National Standards Authority of Ireland (NSAI) produces the following categories of formal documents:

I.S. xxx: Irish Standard — national specification based on the consensus of an expert panel and subject to public consultation.

S.R. xxx: Standard Recommendation — recommendation based on the consensus of an expert panel and subject to public consultation.

SWiFT xxx: A rapidly developed recommendatory document based on the consensus of the participants of an NSAI workshop.

This document replaces/revises/consolidates the NSAI adoption of the document(s) indicated on the CEN/CENELEC cover/Foreword and the following National document(s):

NOTE: The date of any NSAI previous adoption may not match the date of its original CEN/CENELEC document.

This document is based on:

EN IEC 61190-1-3:2018

Published:

2018-03-09

*This document was published
under the authority of the NSAI
and comes into effect on:*

2018-03-27

ICS number:

31.190

NOTE: If blank see CEN/CENELEC cover page

NSAI
1 Swift Square,
Northwood, Santry
Dublin 9

T +353 1 807 3800
F +353 1 807 3838
E standards@nsai.ie
W NSAI.ie

Sales:
T +353 1 857 6730
F +353 1 857 6729
W standards.ie

Údarás um Chaighdeáin Náisiúnta na hÉireann

National Foreword

I.S. EN IEC 61190-1-3:2018 is the adopted Irish version of the European Document EN IEC 61190-1-3:2018, Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solder for electronic soldering applications

This document does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

For relationships with other publications refer to the NSAI web store.

Compliance with this document does not of itself confer immunity from legal obligations.

In line with international standards practice the decimal point is shown as a comma (,) throughout this document.

This page is intentionally left blank

EUROPEAN STANDARD

EN IEC 61190-1-3

NORME EUROPÉENNE

EUROPÄISCHE NORM

March 2018

ICS 31.190

Supersedes EN 61190-1-3:2007

English Version

**Attachment materials for electronic assembly - Part 1-3:
Requirements for electronic grade solder alloys and fluxed and
non-fluxed solid solder for electronic soldering applications
(IEC 61190-1-3:2017)**

Matériaux de fixation pour les assemblages électroniques -
Partie 1-3: Exigences relatives aux alliages à braser de
catégorie électronique et brasure solide fluxée et non-fluxée
pour les applications de brasage électronique
(IEC 61190-1-3:2017)

Verbindungsmaterialien für Baugruppen der Elektronik - Teil
1-3: Anforderungen an Elektroniklote und an Festformlote
mit oder ohne Flussmittel für das Löten von
Elektronikprodukten
(IEC 61190-1-3:2017)

This European Standard was approved by CENELEC on 2018-01-17. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, Former Yugoslav Republic of Macedonia, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.



European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61190-1-3:2018 (E)**European foreword**

The text of document 91/1468/FDIS, future edition 3 of IEC 61190-1-3, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61190-1-3:2018.

The following dates are fixed:

- latest date by which the document has to be (dop) 2018-10-17
implemented at national level by
publication of an identical national
standard or by endorsement
- latest date by which the national (dow) 2021-01-17
standards conflicting with the
document have to be withdrawn

This document supersedes EN 61190-1-3:2017 and EN 61190-1-3:2017/A1:2010.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 61190-1-3:2017 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61189-5 (series)	NOTE	Harmonized as EN 61189-5 (series).
IEC 61189-6	NOTE	Harmonized as EN 61189-6
ISO 9453	NOTE	Harmonized as EN ISO 9453.
ISO 9454-1	NOTE	Harmonized as EN ISO 9454-1.
ISO 9454-2	NOTE	Harmonized as EN ISO 9454-2.

This is a free preview. Purchase the entire publication at the link below:

[Product Page](#)

-
- Looking for additional Standards? Visit Intertek Inform Infostore
 - Learn about LexConnect, All Jurisdictions, Standards referenced in Australian legislation
-